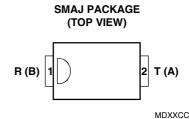
Copyright © 2001, Power Innovations Limited, UK

AUGUST 2001 - REVISED DECEMBER 2001

TELECOMMUNICATION SYSTEM 50 A 10/1000 OVERVOLTAGE PROTECTORS

- 4 kV 10/700, 100 A 5/310 ITU-T K.20/21 rating
- SMA (DO-214AC) Package 25 % Smaller Placement Area than SMB
- Ion-Implanted Breakdown Region Precise and Stable Voltage Low Voltage Overshoot under Surge

DEVICE	V _{DRM}	V _(BO)
DEVICE	v	v
'4070	58	70
'4080	65	80
'4090	68	90
'4095	75	95
'4115	90	115
'4125	100	125
'4145	120	145
'4165	135	165
'4180	145	180
'4200	155	200
'4220	160	220
'4240	180	240
'4250	190	250
'4265	200	265
'4290	220	290
'4320	240	320
'4300	230	300
'4350	275	350
'4360	290	360
'4395	320	395



device symbol



Terminals T and R correspond to the alternative line designators of A and B

Rated for International Surge Wave Shapes.

WAVE SHAPE	STANDARD	I _{TSP} A
2/10 µs	GR-1089-CORE	300
8/20 µs	IEC 61000-4-5	220
10/160 µs	FCC Part 68	120
10/700 µs	ITU-T K.20/21/45	100
10/560 µs	FCC Part 68	75
10/1000 µs	GR-1089-CORE	50

HOW TO ORDER

DEVICE	PACKAGE	CARRIER	ORDER AS	
TISP4xxxM3AJ	AJ (J-Bend DO-214AC/SMA)	Embossed Tape Reeled	TISP4xxxM3AJR	
Insert xxx value corresponding to protection voltages of 070, 080, 090, 095 etcetera.				

description

These devices are designed to limit overvoltages on the telephone line. Overvoltages are normally caused by a.c. power system or lightning flash disturbances which are induced or conducted on to the telephone line. A single device provides 2-point protection and is typically used for the protection of 2-wire telecommunication equipment (e.g. between the Ring and Tip wires for telephones and modems). Combinations of devices can be used for multi-point protection (e.g. 3-point protection between Ring, Tip and Ground).

The protector consists of a symmetrical voltage-triggered bidirectional thyristor. Overvoltages are initially clipped by breakdown clamping until the voltage rises to the breakover level, which causes the device to crowbar into a low-voltage on state. This low-voltage on state causes the current resulting from the overvoltage to be safely diverted through the device. The high crowbar holding current prevents d.c. latchup as the diverted current subsides.

PRODUCT INFORMATION

Information is current as of publication date. Products conform to specifications in accordance with the terms of Power Innovations standard warranty. Production processing does not necessarily include testing of all parameters.



AUGUST 2001 - REVISED DECEMBER 2001

The TISP4xxxM3AJ range consists of twenty voltage variants to meet various maximum system voltage levels (58 V to 320 V). They are guaranteed to voltage limit and withstand the listed international lightning surges in both polarities. These medium (M) current protection devices are in a plastic package SMAJ (JEDEC DO-214AC with J-bend leads) and supplied in embossed tape reel pack. For alternative voltage and holding current values, consult the factory. For higher rated impulse currents, the 100 A 10/1000 TISP4xxxH3BJ series in the SMB (JEDEC DO-214AA) package is available.

absolute maximum ratings, T_A = 25 °C (unless otherwise noted)

RATING	SYMBOL	VALUE	UNI
'4070		± 58	
⁴ 080		± 65	
⁽⁴⁰⁹⁰⁾		± 68	
4095		± 75	
'4115		± 90	
'4125		±100	
·4145		±120	
'4165		±135	
'4180		±145	
Paratitiva people off state unliteral (see Nate 1) (4200	N/	±155	
Repetitive peak off-state voltage, (see Note 1) 4220	V _{DRM}	±160	V
'4240		±180	
'4250		±190	
'4265		±200	
'4290		±220	
'4300		±230	
'4320		± 240	
'4350		±275	
'4360		±290	
4395		±320	
Non-repetitive peak on-state pulse current (see Notes 2, 3 and 4)			
2/10 μs (GR-1089-CORE, 2/10 μs voltage wave shape)		300	
8/20 μs (IEC 61000-4-5, combination wave generator, 1.2/50 voltage, 8/20 current)		220	
10/160 μs (FCC Part 68, 10/160 μs voltage wave shape)		120	
5/200 µs (VDE 0433, 10/700 µs voltage wave shape)		110	
0.2/310 μs (I3124, 0.5/700 μs voltage wave shape)	I _{TSP}	100	А
5/310 µs (ITU-T K.20/21/45, K.44 10/700 µs voltage wave shape)		100	
5/310 μs (FTZ R12, 10/700 μs voltage wave shape)		100	
10/560 μs (FCC Part 68, 10/560 μs voltage wave shape)		75	
10/1000 μs (GR-1089-CORE, 10/1000 μs voltage wave shape)		50	
Non-repetitive peak on-state current (see Notes 2, 3 and 5)			
20 ms (50 Hz) full sine wave		23	
16.7 ms (60 Hz) full sine wave	I _{TSM}	24	А
1000 s 50 Hz/60 Hz a.c.		1.6	
Initial rate of rise of on-state current, Exponential current ramp, Maximum ramp value < 100 A	di _T /dt	300	A/µ
Junction temperature	ТJ	-40 to +150	°C
Storage temperature range	T _{stg}	-65 to +150	°(

NOTES: 1. See Applications Information and Figure 10 for voltage values at lower temperatures.

2. Initially the TISP4xxxM3AJ must be in thermal equilibrium with $T_{J} = 25 \text{ °C}$.

3. The surge may be repeated after the TISP4xxxM3AJ returns to its initial conditions.

4. See Applications Information and Figure 11 for current ratings at other temperatures.

 EIA/JESD51-2 environment and EIA/JESD51-3 PCB with standard footprint dimensions connected with 5 A rated printed wiring track widths. See Figure 9 for the current ratings at other durations. Derate current values at -0.61 %/°C for ambient temperatures above 25 °C

AUGUST 2001 - REVISED DECEMBER 2001

	PARAMETER	TEST CONDITIONS		MIN	TYP	MAX	UNIT
I _{DRM}	Repetitive peak off-	V _D = V _{DRM}	T _A = 25 °C			±5	μA
DRM	state current		T _A = 85 °C			±10	μ
			'4070			±70	
			'4080			±80	
			'4090			±90	
			'4095			±95	
			'4115			±115	
			'4125			±125	
			'4145			±145	
			'4165			±165	
			'4180			±180	
	Dreakovarvaltara		'4200			±200	v
V _(BO)	Breakover voltage	$dv/dt = \pm 250 \text{ V/ms}, \text{ R}_{SOURCE} = 300 \Omega$	'4220			±220	v
			'4240			±240	
			'4250			±250	
			'4265			±265	
			'4290			±290	
			'4300			±300	
			'4320			±320	
			'4350			±350	
			'4360			±360	
			'4395			±395	
			'4070			±78	
			'4080			±88	
			'4090			±98	
		'4095			±102		
		'4115			±122		
		'4125			±132		
			'4145			±151	
			'4165			±171	
		dv/dt $\leq \pm 1000$ V/µs, Linear voltage ramp,	'4180			±186	
	Impulse breakover	Maximum ramp value = $\pm 500 \text{ V}$	'4200			±207	
V _(BO)	voltage	$di/dt = \pm 20 \text{ A}/\mu\text{s}$, Linear current ramp,	·4220			±227	V
	ronago	Maximum ramp value = $\pm 10 \text{ A}$	·4240			±247	
			·4250			±257	
			·200			+272	
			·4290			±298	
			·4300			±308	
			'4320			±328	
			·4350			±359	
			'4360			±370	
			·4395			±405	
(BO)	Breakover current	dv/dt = ± 250 V/ms, R _{SOURCE} = 300 Ω	-1000	±0.15		±405 ±0.6	А
(BO) VT	On-state voltage	$I_T = \pm 5 \text{ A, } t_W = 100 \ \mu \text{s}$		-0.10		±0.0	V
vı H	Holding current	$I_T = \pm 5 \text{ A}, \text{ ti/dt} = \pm -30 \text{ mA/ms}$		±0.15		±0.35	A
dv/dt	Critical rate of rise of off-state voltage	Linear voltage ramp, Maximum ramp value < 0.85V _{DRM}		±5		10.00	kV/µs
ID	Off-state current	V _D = ±50 V	T _A = 85 °C			±10	μA
ע			IA = 05 0			±10	μΛ

electrical characteristics, T_A = 25 °C (unless otherwise noted)



AUGUST 2001 - REVISED DECEMBER 2001

electrical characteristics, $T_A = 25$ °C (unless otherwise noted) (continued)

	PARAMETER		TEST CONDITIONS	6	MIN	TYP	MAX	UNIT
		f = 1 MHz,	$V_d = 1 V rms, V_D = 0,$	4070 thru '4115		83	100	
				'4125 thru '4220		62	74	
				'4240 thru '4395		50	60	
		f = 1 MHz,	$V_d = 1 V rms, V_D = -1 V$	'4070 thru '4115		78	94	
				'4125 thru '4220		56	67	
				'4240 thru '4395		45	54	
<u> </u>	Off-state capacitance	f = 1 MHz,	$V_d = 1 V rms, V_D = -2 V$	'4070 thru '4115		72	87	pF
Coff	OII-State capacitance			'4125 thru '4220		52	62	рг
				'4240 thru '4395		42	50	
		f = 1 MHz,	$V_d = 1 V rms$, $V_D = -50 V$	'4070 thru '4115		36	44	
				'4125 thru '4220		26	31	
				'4240 thru '4395		19	22	
		f = 1 MHz,	$V_{d} = 1 \text{ V rms}, V_{D} = -100 \text{ V}$	'4125 thru '4220		21	25	
		(see Note 6))	'4240 thru '4395		15	18	

NOTE 6: To avoid possible voltage clipping, the '4125 is tested with $V_D = -98$ V.

thermal characteristics

	PARAMETER	TEST CONDITIONS	MIN	ТҮР	MAX	UNIT
Rela Junction to free air thermal resistance	EIA/JESD51-3 PCB, I _T = I _{TSM(1000)} , T _A = 25 °C, (see Note 7)			115	°C/W	
R _{θJA}		265 mm x 210 mm populated line card, 4-layer PCB, $I_T = I_{TSM(1000)}$, $T_A = 25 \text{ °C}$		52		0/11

NOTE 7: EIA/JESD51-2 environment and PCB has standard footprint dimensions connected with 5 A rated printed wiring track widths.

AUGUST 2001 - REVISED DECEMBER 2001

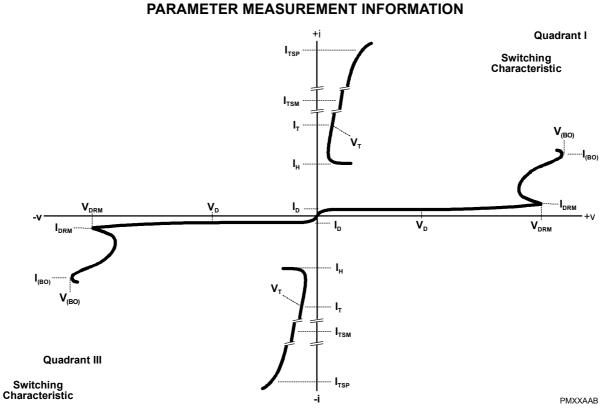


Figure 1. VOLTAGE-CURRENT CHARACTERISTIC FOR T AND R TERMINALS ALL MEASUREMENTS ARE REFERENCED TO THE R TERMINAL



AUGUST 2001 - REVISED DECEMBER 2001

TYPICAL CHARACTERISTICS

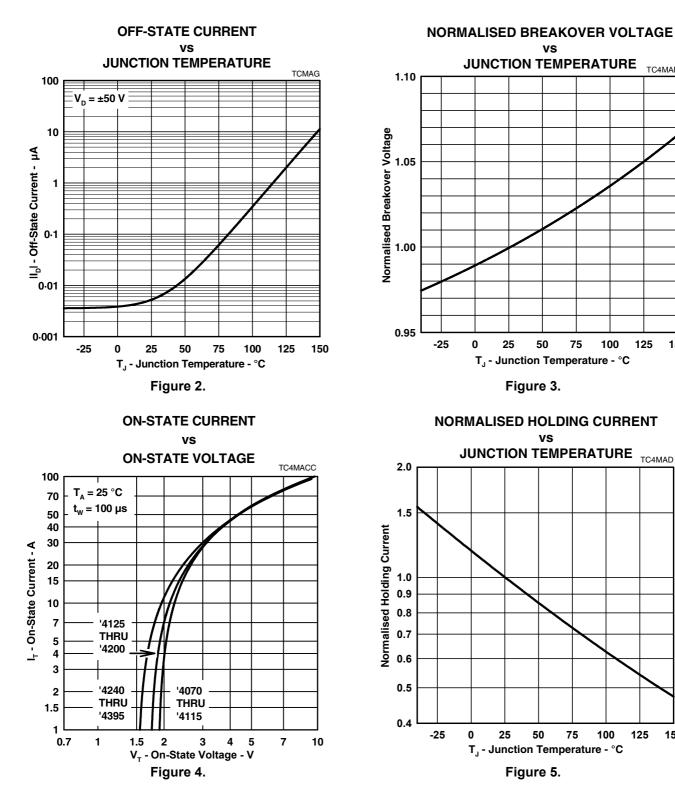
TC4MAF

125

125

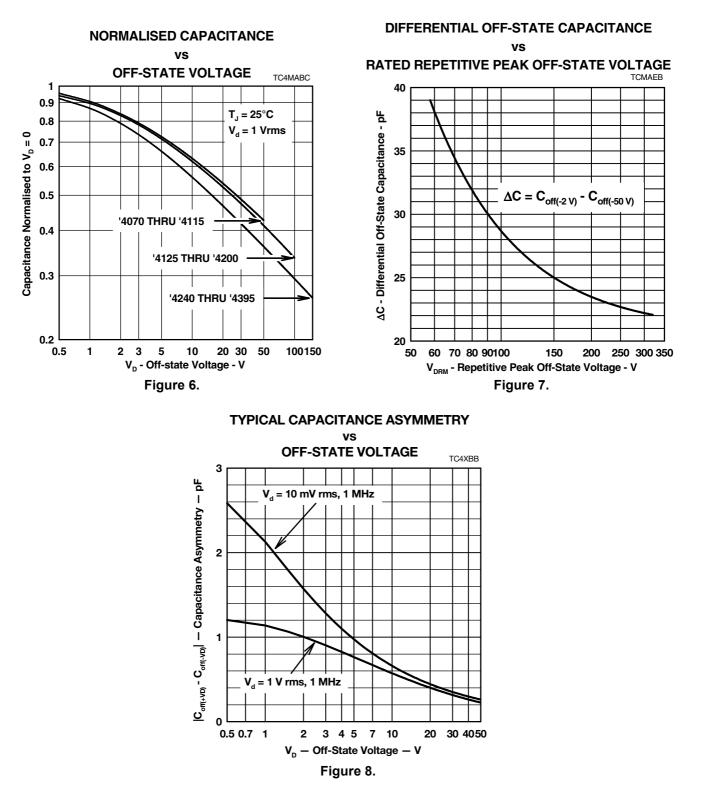
150

150



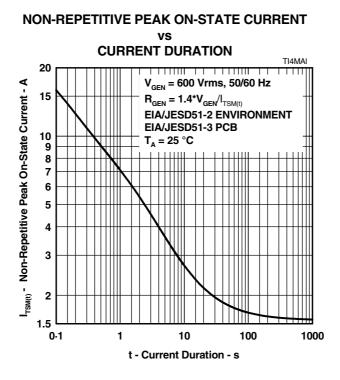
AUGUST 2001 - REVISED DECEMBER 2001

TYPICAL CHARACTERISTICS

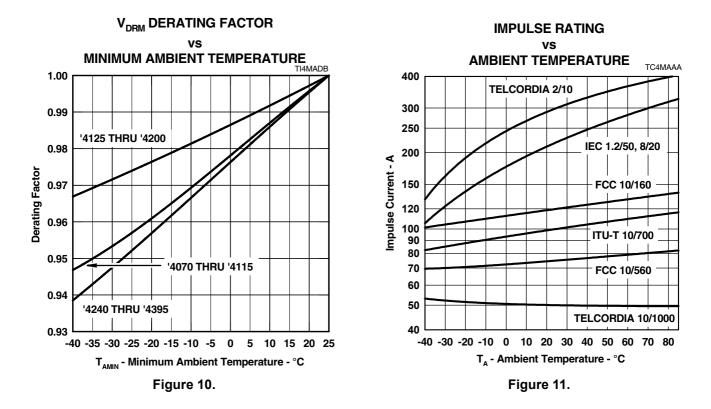




RATING AND THERMAL INFORMATION





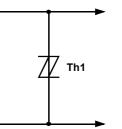


AUGUST 2001 - REVISED DECEMBER 2001

APPLICATIONS INFORMATION

deployment

These devices are two terminal overvoltage protectors. They may be used either singly to limit the voltage between two conductors (Figure 12) or in multiples to limit the voltage at several points in a circuit (Figure 13).



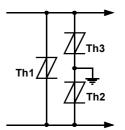


Figure 12. TWO POINT PROTECTION



In Figure 12, protector Th1 limits the maximum voltage between the two conductors to $\pm V_{(BO)}$. This configuration is normally used to protect circuits without a ground reference, such as modems. In Figure 13, protectors Th2 and Th3 limit the maximum voltage between each conductor and ground to the $\pm V_{(BO)}$ of the individual protector. Protector Th1 limits the maximum voltage between the two conductors to its $\pm V_{(BO)}$ value. If the equipment being protected has all its vulnerable components connected between the conductors and ground, then protector Th1 is not required.

impulse testing

To verify the withstand capability and safety of the equipment, standards require that the equipment is tested with various impulse wave forms. The table below shows some common values.

STANDARD	PEAK VOLTAGE SETTING	VOLTAGE WAVE FORM	PEAK CURRENT VALUE	CURRENT WAVE FORM	TISP4xxxM3 25 °C RATING	SERIES RESISTANCE	
	v	μs	Α	μs	Α	Ω	
GR-1089-CORE	2500	2/10	500	2/10	300	11	
GH-1009-CONL	1000	10/1000	100	10/1000	50		
	1500	10/160	200	10/160	120	2x5.6	
FCC Part 68	800	10/560	100	10/560	75	3	
(March 1998)	1500	9/720 †	37.5	5/320 †	100	0	
	1000	9/720 †	25	5/320 †	100	0	
13124	1500	0.5/700	37.5	0.2/310	100	0	
ITU-T K.20/K.21	1500	10/700	37.5	5/210	100	0	
110-1 K.20/K.21	4000	10/700	100	5/310 100		0	

† FCC Part 68 terminology for the waveforms produced by the ITU-T recommendation K.21 10/700 impulse generator

If the impulse generator current exceeds the protectors current rating then a series resistance can be used to reduce the current to the protectors rated value and so prevent possible failure. The required value of series resistance for a given waveform is given by the following calculations. First, the minimum total circuit impedance is found by dividing the impulse generators peak voltage by the protectors rated current. The impulse generators fictive impedance (generators peak voltage divided by peak short circuit current) is then subtracted from the minimum total circuit impedance to give the required value of series resistance.

For the FCC Part 68 10/560 waveform the following values result. The minimum total circuit impedance is $800/75 = 10.7 \Omega$ and the generators fictive impedance is $800/100 = 8 \Omega$. This gives a minimum series resistance value of $10.7 - 8 = 2.7 \Omega$. After allowing for tolerance, a $3 \Omega \pm 10\%$ resistor would be suitable. The 10/160 waveform needs a standard resistor value of 5.6 Ω per conductor. These would be R1a and R1b in



AUGUST 2001 - REVISED DECEMBER 2001

Figure 15 and Figure 16. FCC Part 68 allows the equipment to be non-operational after the 10/160 (conductor to ground) and 10/560 (inter-conductor) impulses. The series resistor value may be reduced to zero to pass FCC Part 68 in a non-operational mode e.g. Figure 14. For this type of design, the series fuse must open before the TISP4xxxM3 fails. For Figure 14, the maximum fuse i²t is 2.3 A²s. In some cases the equipment will require verification over a temperature range. By using the rated waveform values from Figure 11, the appropriate series resistor value can be calculated for ambient temperatures in the range of -40 °C to 85 °C.

a.c. power testing

The protector can withstand currents applied for times not exceeding those shown in Figure 9. Currents that exceed these times must be terminated or reduced to avoid protector failure. Fuses, PTC (Positive Temperature Coefficient) resistors and fusible resistors are overcurrent protection devices which can be used to reduce the current flow. Protective fuses may range from a few hundred milliamperes to one ampere. In some cases it may be necessary to add some extra series resistance to prevent the fuse opening during impulse testing. The current versus time characteristic of the overcurrent protector must be below the line shown in Figure 9. In some cases there may be a further time limit imposed by the test standard (e.g. UL 1459 wiring simulator failure).

capacitance

The protector characteristic off-state capacitance values are given for d.c. bias voltage, V_D , values of 0, -1 V, -2 V and -50 V. Where possible values are also given for -100 V. Values for other voltages may be calculated by multiplying the $V_D = 0$ capacitance value by the factor given in Figure 6. Up to 10 MHz the capacitance is essentially independent of frequency. Above 10 MHz the effective capacitance is strongly dependent on connection inductance. In many applications, such as Figure 15 and Figure 17, the typical conductor bias voltages will be about -2 V and -50 V. Figure 7 shows the differential (line unbalance) capacitance caused by biasing one protector at -2 V and the other at -50 V.

Figure 8 shows the typical capacitance asymmetry; the difference between the capacitance measured with a positive value of V_D and the capacitance value when the polarity of V_D is reversed. Capacitance asymmetry is an important parameter in ADSL systems where the protector often has no d.c. bias and the signal level is in the region of ±10 V.

normal system voltage levels

The protector should not clip or limit the voltages that occur in normal system operation. For unusual conditions, such as ringing without the line connected, some degree of clipping is permissible. Under this condition about 10 V of clipping is normally possible without activating the ring trip circuit.

Figure 10 allows the calculation of the protector V_{DRM} value at temperatures below 25 °C. The calculated value should not be less than the maximum normal system voltages. The TISP4265M3AJ, with a V_{DRM} of 200 V, can be used for the protection of ring generators producing 100 V rms of ring on a battery voltage of -58 V (Th2 and Th3 in Figure 17). The peak ring voltage will be 58 + 1.414*100 = 199.4 V. However, this is the open circuit voltage and the connection of the line and its equipment will reduce the peak voltage. In the extreme case of an unconnected line, clipping the peak voltage to 190 V should not activate the ring trip. This level of clipping would occur at the temperature when the V_{DRM} has reduced to 190/200 = 0.95 of its 25 °C value. Figure 10 shows that this condition will occur at an ambient temperature of -28 °C. In this example, the TISP4265M3AJ will allow normal equipment operation provided that the minimum expected ambient temperature does not fall below -28 °C.

JESD51 thermal measurement method

To standardise thermal measurements, the EIA (Electronic Industries Alliance) has created the JESD51 standard. Part 2 of the standard (JESD51-2, 1995) describes the test environment. This is a 0.0283 m³ (1 ft³) cube which contains the test PCB (Printed Circuit Board) horizontally mounted at the centre. Part 3 of the

standard (JESD51-3, 1996) defines two test PCBs for surface mount components; one for packages smaller than 27 mm on a side and the other for packages up to 48 mm. The SMAJ measurements used the smaller 76.2 mm x 114.3 mm (3.0 " x 4.5 ") PCB. The JESD51-3 PCBs are designed to have low effective thermal conductivity (high thermal resistance) and represent a worse case condition. The PCBs used in the majority of applications will achieve lower values of thermal resistance and so can dissipate higher power levels than indicated by the JESD51 values.

Power INNOVATIONS

AUGUST 2001 - REVISED DECEMBER 2001

typical circuits

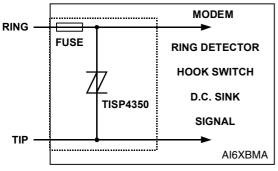
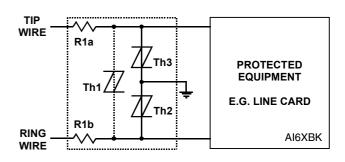
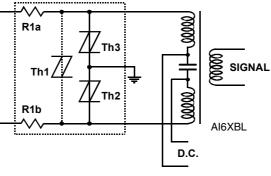


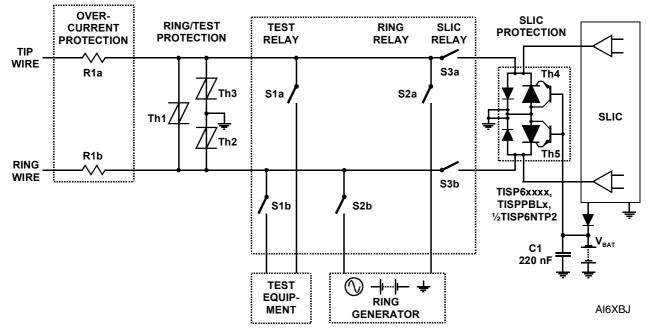
Figure 14. MODEM INTER-WIRE PROTECTION









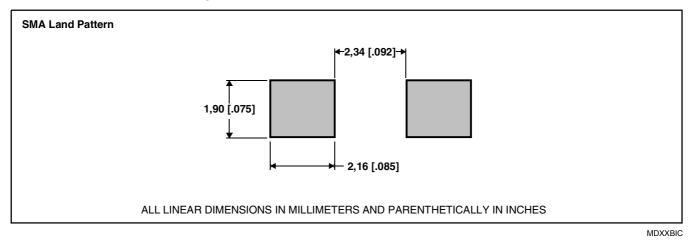




AUGUST 2001 - REVISED DECEMBER 2001

MECHANICAL DATA

recommended printed wiring land pattern dimensions.



device symbolization code

Devices will be coded as below. As the device parameters are symmetrical, terminal 1 is not identified.

DEVICE	SYMBOLIZATION CODE
TISP4070M3AJ	4070M
TISP4080M3AJ	4080M
TISP4090M3AJ	4090M
TISP4095M3AJ	4095M
TISP4115M3AJ	4115M
TISP4125M3AJ	4125M
TISP4145M3AJ	4145M
TISP4165M3AJ	4165M
TISP4180M3AJ	4180M
TISP4200M3AJ	4200M
TISP4220M3AJ	4220M
TISP4240M3AJ	4240M
TISP4250M3AJ	4250M
TISP4265M3AJ	4265M
TISP4290M3AJ	4290M
TISP4300M3AJ	4300M
TISP4320M3AJ	4320M
TISP4350M3AJ	4350M
TISP4360M3AJ	4360M
TISP4395M3AJ	4395M

carrier information

For production quantities the carrier will be embossed tape reel pack. Evaluation quantities may be shipped in bulk pack or embossed tape.

CARRIER	STANDARD QUANTITY
Embossed Tape Reel Pack	5 000





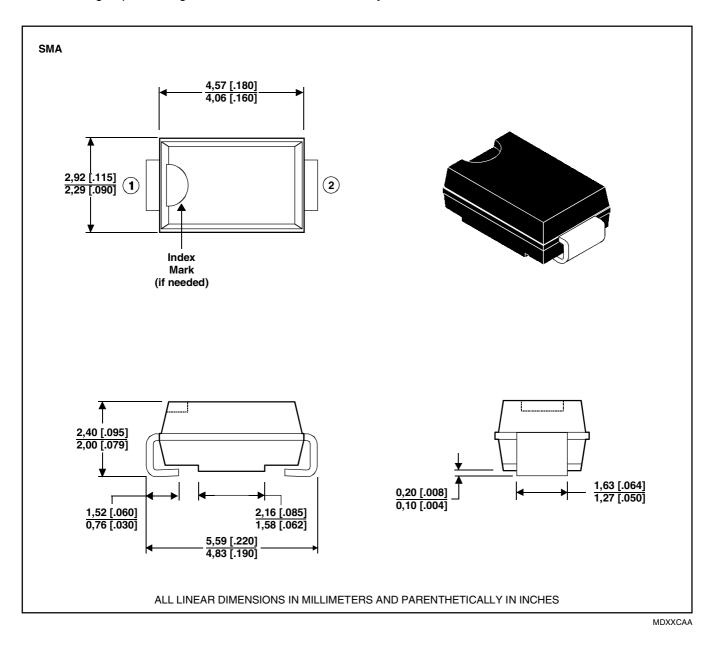
AUGUST 2001 - REVISED DECEMBER 2001

MECHANICAL DATA

SMAJ (DO-214AC)

plastic surface mount diode package

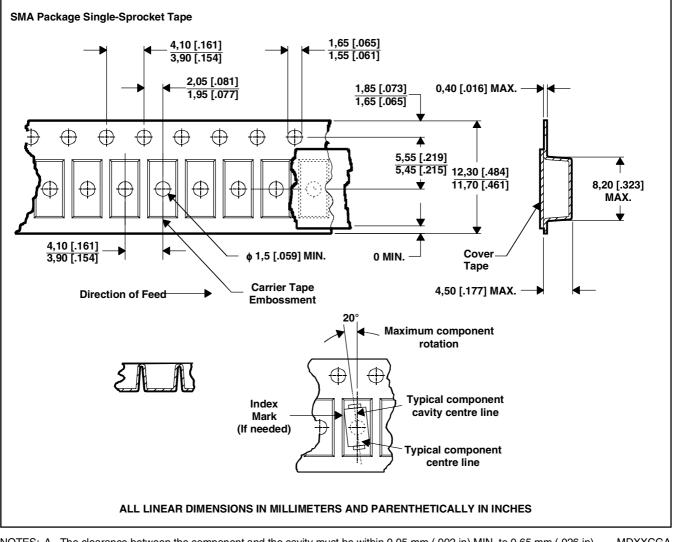
This surface mount package consists of a circuit mounted on a lead frame and encapsulated within a plastic compound. The compound will withstand soldering temperature with no deformation, and circuit performance characteristics will remain stable when operated in high humidity conditions. Leads require no additional cleaning or processing when used in soldered assembly.



AUGUST 2001 - REVISED DECEMBER 2001

MECHANICAL DATA

tape dimensions



- NOTES: A. The clearance between the component and the cavity must be within 0,05 mm (.002 in) MIN. to 0,65 mm (.026 in) MDXXCGA MAX. so that the component cannot rotate more than 20° within the determined cavity.
 - B. Taped devices are supplied on a reel of the following dimensions:-

Reel diameter:	330 mm ±3,0 mm (12.99 in ±.12 in)
Reel hub diameter	75 mm (2.95 in) MIN.
Reel axial hole:	13,0 mm ±0,5 mm (.51 in ±.02 in)

C. 5 000 devices per reel.



IMPORTANT NOTICE

Power Innovations Limited (PI) reserves the right to make changes to its products or to discontinue any semiconductor product or service without notice, and advises its customers to verify, before placing orders, that the information being relied on is current.

PI warrants performance of its semiconductor products to the specifications applicable at the time of sale in accordance with PI's standard warranty. Testing and other quality control techniques are utilized to the extent PI deems necessary to support this warranty. Specific testing of all parameters of each device is not necessarily performed, except those mandated by government requirements.

PI assumes no liability for applications assistance, customer product design, software performance, or infringement of patents or services described herein. Nor is any license, either express or implied, granted under any patent right, copyright, design right, or other intellectual property right of PI covering or relating to any combination, machine, or process in which such semiconductor products or services might be or are used.

PI SEMICONDUCTOR PRODUCTS ARE NOT DESIGNED, INTENDED, AUTHORISED, OR WARRANTED TO BE SUITABLE FOR USE IN LIFE-SUPPORT APPLICATIONS, DEVICES OR SYSTEMS.

Copyright © 2001, Power Innovations Limited